IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

pplication Serial No.10/734,419 Filing Date...... December 11, 2003 Inventor......John T. Moore et al. Assignee Micron Technology, Inc. Title: Semiconductor Wafer Assemblies Comprising Photoresist Over Silicon Nitride Materials

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

To:

Mail Stop Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

From:

Jennifer J. Taylor, Ph.D. (Tel. 509-624-4276; Fax 509-838-3424)

Wells St. John P.S.

601 W. First Avenue, Suite 1300

Spokane, WA 99201-3828

Dear Sir:

The Examiner's attention is directed to the references which are listed on the attached Form PTO-1449.

Citation of these references is respectfully requested.

A check in the amount of \$180.00 is enclosed to cover the fee specified under 37 C.F.R. § 1.17(p).

Respectfully submitted,

Dated: May 19, 2005

By:

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Form PTO-1449

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

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ATTY. DOCKET NO. M122-2463

SERIAL NO. 10/734,419

APPLICANT John T. Moore et al.

FILING DATE December 11, 2003 GROUP 2815

U.S. PATENT DOCUMENTS

Examiner Initial		Document Number	Date	Name	Class	Subclass	Fili If Ap	ng Date propriate		
	AA	6,756,634	06-2004	Helm et al.						
	AB									
	AC	-								
	AD						:			
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EXAMINER		DATE CONSIDERED								

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.